RELIABILITY REPORT

FOR

MAX834EUK+T

PLASTIC ENCAPSULATED DEVICES

January 15, 2013

MAXIM INTEGRATED

160 RIO ROBLES

SAN JOSE, CA 95134

Approved by
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Quality Assurance
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Conclusion

The MAX834EUK+T successfully meets the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

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I. Device Description

A. General

The MAX834/MAX835 micropower voltage monitors contain a 1.204V precision bandgap reference, comparator, and latched output in a 5-pin SOT23 package. Using the latched output prevents deep discharge of batteries. The MAX834 has an open-drain, n-channel output driver, while the MAX835 has a push-pull output driver. Two external resistors set the trip-threshold voltage. The MAX834/MAX835 feature a level-sensitive latch, eliminating the need to add hysteresis to prevent oscillations in battery-load-disconnect applications.

II. Manufacturing Information

A. Description/Function:	Micropower, Latching Voltage Monitors in SOT23-5
B. Process:	S3
C. Number of Device Transistors:	86
D. Fabrication Location:	USA
E. Assembly Location:	Malaysia, Thailand and Philippines
F. Date of Initial Production:	May 1995

III. Packaging Information

A. Package Type:	5-pin SOT23
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1601-0017
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	324.3°C/W
K. Single Layer Theta Jc:	82°C/W
L. Multi Layer Theta Ja:	255.9°C/W
M. Multi Layer Theta Jc:	81°C/W

IV. Die Information

A. Dimensions:	48X38 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	3 microns (as drawn)
F. Minimum Metal Spacing:	3 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Richard Aburano (Manager, Reliability Engineering) Don Lipps (Manager, Reliability Engineering) Bryan Preeshl (Vice President of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 160 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 6.9 \times 10^{-9}$

$\lambda = 6.9$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maximintegrated.com/qa/reliability/monitor. Cumulative monitor data for the S3 Process results in a FIT Rate of 0.03 @ 25C and 0.56 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing

The MS08-2 die type has been found to have all pins able to withstand a transient pulse of:

ESD-HBM:	+/- 2500V per JEDEC JESD22-A114 (lot NNECDA043H, D/C 0726)
ESD-CDM:	+/- 750V per JEDEC JESD22-C101 (lot NNECDA043H, D/C 0726)

Latch-Up testing has shown that this device withstands a current of +/- 75mA and overvoltage per JEDEC JESD78 (lot NNECCA034C, D/C 0619 & lot NNECDA043H, D/C 0726).

Table 1

Reliability Evaluation Test Results

MAX834EUK+T

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)					
	Ta = 135C Biased Time = 192 hrs.	DC Parameters & functionality	160	0	XNEDBQ001A

Note 1: Life Test Data may represent plastic DIP qualification lots.